

NCE N-Channel Super Trench Power MOSFET

Description

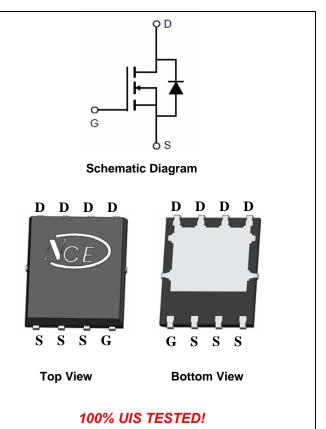
The NCEP1550G uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

General Features

- $V_{DS} = 150V, I_D = 50A$ $R_{DS(ON)} < 25m\Omega @ V_{GS} = 10V$
- Excellent gate charge x R_{DS(on)} product(FOM)
- Very low on-resistance R_{DS(on)}
- 175 °C operating temperature
- Pb-free lead plating
- 100% UIS tested

Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification



100% ΔVds TESTED!

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCEP1550G	NCEP1550G	DFN5X6-8L	-	-	-

Absolute Maximum Ratings (T_C=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	150	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	I _D	50	Α
Drain Current-Continuous(T _C =100 °C)	I _D (100℃)	35.4	Α
Pulsed Drain Current	I _{DM}	200	Α
Maximum Power Dissipation	P _D	125	W
Derating factor		1	W/℃
Single pulse avalanche energy (Note 5)	E _{AS}	210	mJ
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	$^{\circ}$ C

Thermal Characteristic

Thermal Resistance,Junction-to-Case ^(Note 2)	R _{eJC}	1	°C/W
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NCEP1550G

Electrical Characteristics (T_C=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	150		-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =150V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V_{GS} =±20 V , V_{DS} =0 V	-	-	±100	nA
On Characteristics (Note 3)			1	l .		
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	2.5	-	4.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =30A	-	21	25	mΩ
Forward Transconductance	g FS	V _{DS} =10V,I _D =30A	-	40	-	S
Dynamic Characteristics (Note4)			1	l .		
Input Capacitance	C _{lss}	75,474	-	5000	-	PF
Output Capacitance	Coss	V_{DS} =75 V , V_{GS} =0 V ,	-	192	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz	-	9.5	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$t_{d(on)}$		-	21	-	nS
Turn-on Rise Time	t _r	V_{DD} =75 V , I_D =30 A	-	20	-	nS
Turn-Off Delay Time	$t_{\sf d(off)}$	V_{GS} =10 V , R_{G} =4.7 Ω	-	40	-	nS
Turn-Off Fall Time	t _f		-	10	-	nS
Total Gate Charge	Qg	\/ 7 5\/ 004	-	59.8		nC
Gate-Source Charge	Q_{gs}	$V_{DS}=75V, I_{D}=30A,$	-	28.2		nC
Gate-Drain Charge	Q_{gd}	V _{GS} =10V	-	7.1		nC
Drain-Source Diode Characteristics			1	Į.		
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =30A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	50	Α
Reverse Recovery Time	t _{rr}	$T_J = 25^{\circ}C$, $I_F = I_S$	-	58		nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)}$	-	135		nC

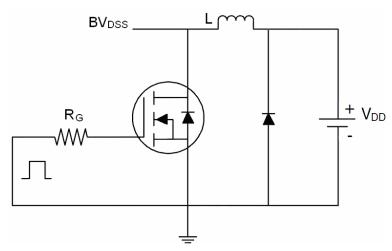
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25 $^{\circ}\!\!\mathrm{C}$,V_DD=50V,V_G=10V,L=0.5mH,Rg=25 Ω

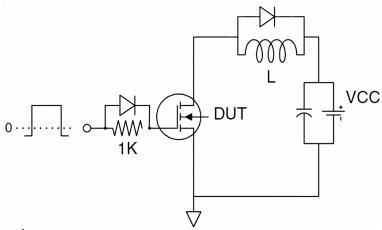


Test Circuit

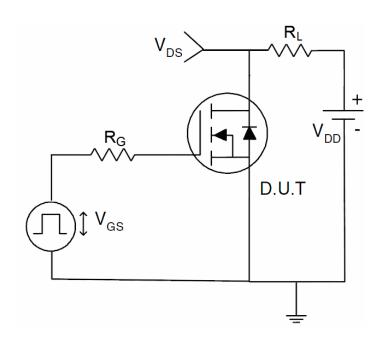
1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit







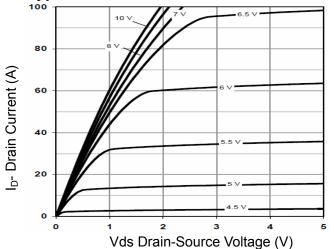


Figure 1 Output Characteristics

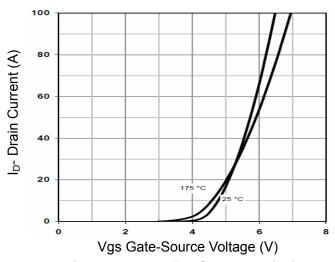


Figure 2 Transfer Characteristics

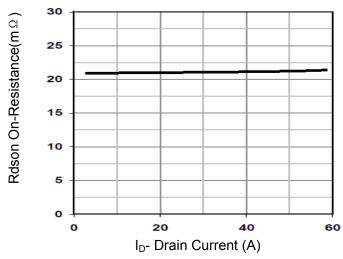


Figure 3 Rdson- Drain Current

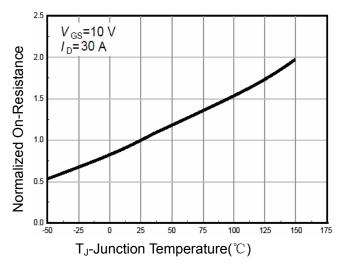


Figure 4 Rdson-JunctionTemperature

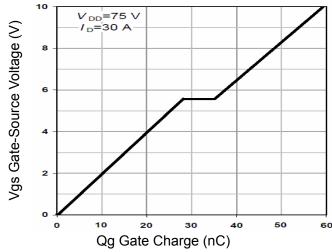


Figure 5 Gate Charge

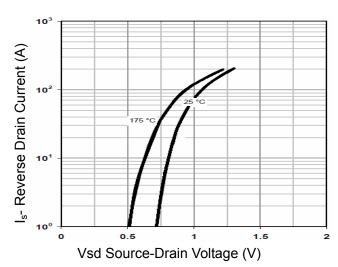
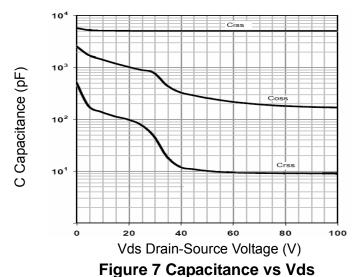


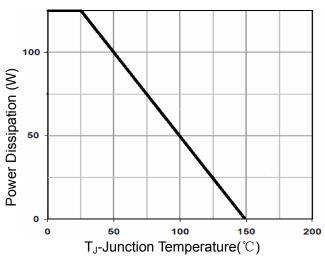
Figure 6 Source- Drain Diode Forward



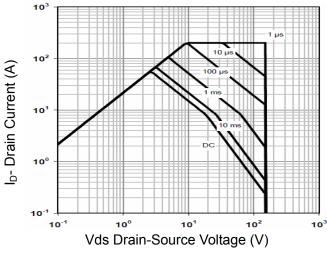
Pb Free Product











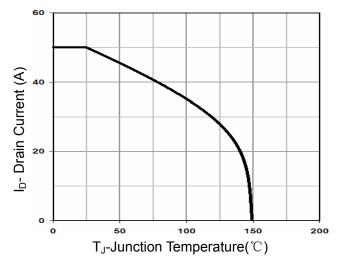
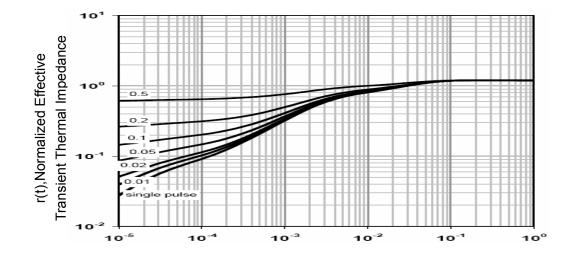


Figure 8 Safe Operation Area

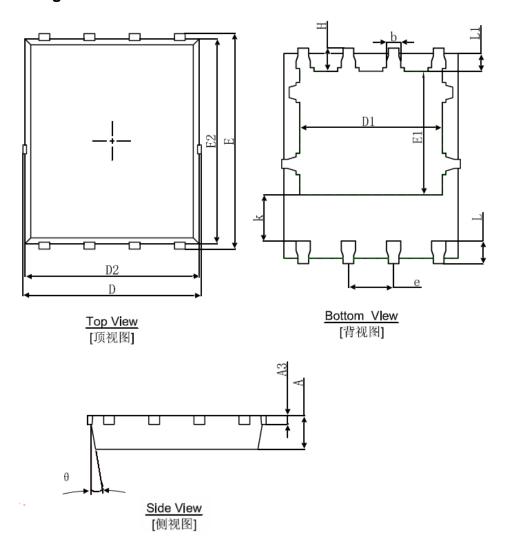
Figure 10 Current De-rating



Square Wave Pluse Duration(sec) **Figure 11 Normalized Maximum Transient Thermal Impedance**



DFN5X6-8L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	0.900	1.000	0.035	0.039	
A3	0.254	0.254REF.		REF.	
D	4.944	5.096	0.195	0.201	
E	5.974	6.126	0.235	0.241	
D1	3.910	4.110	0.154	0.162	
E1	3.375	3.575	0.133	0.141	
D2	4.824	4.976	0.190	0.196	
E2	5.674	5.826	0.223	0.229	
k	1.190	1.390	0.047	0.055	
b	0.350	0.450	0.014	0.018	
е	1.270TYP.		0.050TYP.		
L	0.559	0.711	0.022	0.028	
L1	0.424	0.576	0.017	0.023	
Н	0.574	0.726	0.023	0.029	
θ	8°	12°	8°	12°	



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NCEP1550G

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